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General Description

The MAX5091 high-voltage linear regulator is designed to operate from a +5V to +28V input voltage, and withstands up to 40V transients. The device consumes only 45µA of quiescent current at 100µA output current. The MAX5091 delivers up to 100mA of output current with low 50mV maximum dropout voltage. The MAX5091 provides an active-low open-drain microprocessor RESET output. The reset timeout period is programmable and can be set with an external capacitor. The MAX5091 includes an uncommitted comparator for input voltage monitoring/power-fail indication. The device is available with a fixed +5V (MAX5091A) or +3.3V (MAX5091B) output. The MAX5091 is short-circuit protected and includes thermal shutdown.

The MAX5091 operates over the -40°C to +125°C automotive temperature range and is available in 8-pin, thermally enhanced TDFN and SO-EP packages.

Applications

Automotive Industrial

Home Security/Safety Telecom/Networking

_____Features

- ♦ +5V to +28V Wide Operating Input Voltage Range
- ♦ Withstands 40V Input Voltage Transients
- ♦ Guaranteed 100mA Output Current
- 45μA Typical Quiescent Current at 100μA Output Current
- ♦ Preset +5V (MAX5091A) or +3.3V (MAX5091B) Output Voltage
- ♦ Stable with Only 10µF Output Capacitance
- ♦ RESET Output with Adjustable Timeout Period
- Uncommitted Comparator for Voltage Monitoring/Power-Fail Indication
- ♦ Output Overload and Short-Circuit Protection
- **♦ Thermal Shutdown**
- Available in 8-Pin TDFN (1.95W at T_A = +70°C) and 8-Pin SO (1.5W at T_A = +70°C)
- ♦ Operates Over -40°C to +125°C Automotive Temperature Range

Ordering Information

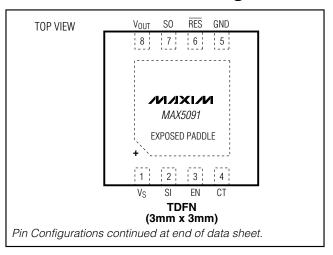
PART	PIN- PACKAGE	PRESET V _{OUT} (V)	PKG CODE	TOP MARK
MAX5091AATA+T	8 TDFN-8	5	T833-2	+APB
MAX5091AASA+	8 SO-EP*	5	S8E-14	_
MAX5091BATA+T	8 TDFN-8	3.3	T833-2	+APC
MAX5091BASA+	8 SO-EP*	3.3	S8E-14	

Note: All devices specified for -40°C to +125°C operating temperature range.

Typical Application Circuit

+5V (MAX5091A)/ +3.3V (MAX5091B) +5V TO +28V 100mÁ VIN C Voli CIN Cout 10uF MIXIM ${ m <}^{ m R\overline{RES}}_{ m 10k}$ MAX5091 $288k\Omega$ RES RESET ${ m <}_{ m 10k}^{ m RS0}$ $100 \text{k}\Omega$ POWER-FAIL

Pin Configurations



MIXIM

Maxim Integrated Products

⁺Denotes lead-free package. *EP = Exposed paddle.

ABSOLUTE MAXIMUM RATINGS

Vs to GND	0.3V to +28V
Vs to GND (t ≤ 1s)	0.3V to +40V
V _{OUT} to GND	0.3V to +20V
	0.3V to +28V
	0.3V to +20V
RES, SO Output Sink Current	5mA
)Continuous
EN, SI to GND	0.3V to +12V
CT to GND	-0.3V to the lower of V _{OUT} or +12V

Continuous Power Dissipation (T _A = +70°C)
8-Pin SO-EP (derate 19.2mW/°C above +70°C)1538mW*
Thermal Resistance (θJA)52°C/W
Thermal Resistance (θ _{JC})6°C/W
8-Pin TDFN-EP (derate 24.4mW/°C above +70°C)1951mW**
Thermal Resistance (θ _{JA})41°C/W
Thermal Resistance (θ _{JC})8.3°C/W
Operating Junction Temperature Range40°C to +125°C
Maximum Junction Temperature+150°C
Storage Temperature Range60°C to +150°C
Lead Temperature (soldering, 10s)+300°C

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS (MAX5091A)

 $(V_S = +14V, V_{OUT} = 5V, EN unconnected, T_A = T_J = -40^{\circ}C$ to $+125^{\circ}C, C_{IN} = 10\mu F, C_{OUT} = 10\mu F, unless otherwise noted. Typical specifications are at <math>T_A = +25^{\circ}C.$) (Note 1)

PARAMETER	SYMBOL		CONDITIONS	MIN	TYP	MAX	UNITS
		$T_A = +25^{\circ}C$, Id	DUT = 1mA	4.95	5	5.05	
Output Voltage		5.6V ≤ V _S ≤ 28	5.6V ≤ V _S ≤ 28V, I _{OUT} = 1mA to 50mA (Note 2)		5	5.10	
	Vout	$5.6V \le V_S \le 40$ (Note 2)	V, t ≤ 1s, I _{OUT} = 1mA to 30mA	4.9	5	5.1	V
		Vs = +8V, Iou	T = 1mA to 100mA	4.9	5	5.1	1
			I _{OUT} = 10mA		0.1	0.25	
Dropout Voltage	V_{DP}	$V_S = +4.75V$	I _{OUT} = 50mA		0.2	0.4	V
			I _{OUT} = 100mA		0.3	0.5	
V _S to V _{OUT} Difference in Undervoltage	V _{IO}	V _S = +4V, I _{OU}	V _S = +4V, I _{OUT} = 35mA			0.4	V
Line Regulation	V _{OL}	+5.5V ≤ V _S ≤ +	+5.5V ≤ V _S ≤ +28V, I _{OUT} = 1mA		0.6	5	mV
Load Regulation	Volo	1mA ≤ I _{OUT} ≤	1mA ≤ I _{OUT} ≤ 100mA		17	50	mV
Current Limit	I _{LIM}				260	400	mA
	IQ	I _{OUT} = 100μA			46	100	
Quiescent Current		Ιουτ = 300μΑ			45	100	μA
		I _{OUT} = 100mA			4.5	10	mA
Shutdown Supply Current	ISHDN	V _{EN} ≤ +0.4V	V _{EN} ≤ +0.4V		17	30	μΑ
Thermal-Shutdown Temperature	TJ(SHDN)	Temperature rising			+165		°C
Thermal-Shutdown Hysteresis	$\Delta T_{J(SHDN)}$				20		°C

^{*}As per JEDEC51 Standard (single-layer board).

^{**}As per JEDEC51 Standard (multilayer board).

ELECTRICAL CHARACTERISTICS (MAX5091A) (continued)

 $(V_S = +14V, V_{OUT} = 5V, EN unconnected, T_A = T_J = -40^{\circ}C \text{ to } +125^{\circ}C, C_{IN} = 10\mu\text{F}, C_{OUT} = 10\mu\text{F}, unless otherwise noted.}$ Typical specifications are at $T_A = +25^{\circ}C$.) (Note 1)

PARAMETER	PARAMETER SYMBOL CONDITIONS		MIN	TYP	MAX	UNITS
RESET			•			•
Reset Threshold Voltage	V _{RT}	V _{OUT} falling	85	90	94.5	%Vout
Reset Threshold Hysteresis	V _{RTH}		30	65	100	mV
Reset Pulse Delay	t _{RD}	C _{CT} = 100nF, t _R ≥ 100μs	55	110	180	ms
RES Output Low Voltage	V_{RL}	$V_S \ge +1.5V, R_{\overline{RES}} = 10k\Omega$ to V_{OUT}			0.4	V
RES Output High Leakage Current	I _{RH}	V _{RES} = 5V			1.0	μΑ
Delay Comparator Threshold	VCTTH	V _{CT} rising	1.9	2.1	2.4	V
Delay Comparator Threshold Hysteresis				100		mV
SENSE						
Sense Threshold	V_{ST}	V _{SI} falling	1.10	1.16	1.24	V
Sense Threshold Hysteresis			50	100	150	mV
Sense Output Low Voltage	V _{SL}	$V_{SI} \le 1.10V$, $V_S \ge 4V$, $R_{SO} = 10k\Omega$ to V_{OUT}			0.4	V
Sense Output Leakage Current	Ish	V _{SO} = 5V, V _{SI} ≥ 1.5V			1	μΑ
Sense Input Current	ISI	V _{SI} = 3.3V	-1		+1	μΑ
ENABLE						
Enable Voltage	VEN	EN = high, regulator on	2.4			V
Lilable Vollage	V EIN	EN = low, regulator off			0.4	v
Enable Internal Pullup Current	I _{EN}	EN is internally pulled up to 3.6V (max)			3	μΑ

ELECTRICAL CHARACTERISTICS (MAX5091B)

 $(V_S = +14V, V_{OUT} = 3.3V, EN unconnected, T_A = T_J = -40^{\circ}C$ to $+125^{\circ}C, C_{IN} = 10\mu F, C_{OUT} = 10\mu F, unless otherwise noted. Typical specifications are at <math>T_A = +25^{\circ}C.$ (Note 1)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
		$T_A = +25$ °C, $I_{OUT} = 1$ mA	3.267	3.3	3.333	
		5V ≤ V _S ≤ 28V, I _{OUT} = 1mA to 50mA (Note 2)	3.234	3.3	3.366	
Output Voltage	Vout	5V ≤ V _S ≤ 40V, t < 1s, I _{OUT} = 1mA to 30mA (Note 2)	3.234	3.3	3.366	V
		$V_S = +8V$, $I_{OUT} = 1$ mA to 100mA	3.234	3.3	3.366	
V _S to V _{OUT} Difference in Undervoltage	VIO	V _S = 3.5V, I _{OUT} = 35mA		0.2	0.4	V
Line Regulation	V _{OL}	5V ≤ V _S ≤ 28V, I _{OUT} = 1mA		0.6	5	mV
Load Regulation	Volo	1mA ≤ I _{OUT} ≤ 100mA		11	40	mV
Current Limit	I _{LIM}		160	260	400	mA
		I _{OUT} = 100μA		45	100	^
Quiescent Current	IQ	I _{OUT} = 300μA		45	100	μΑ
		I _{OUT} = 100mA		4.4	10	mA
Shutdown Supply Current	ISHDN	V _{EN} ≤ 0.4V		17	30	μΑ
Thermal-Shutdown Temperature	TJ <u>(</u> SHDN)	Temperature rising	+165			°C
Thermal-Shutdown Hysteresis	$\Delta T_{J(SHDN)}$		20			°C
RESET CIRCUIT						
Reset Threshold Voltage	V _{RT}	V _{OUT} falling	85	90	94.5	%V _{OUT}
Reset Threshold Hysteresis	V _{RTH}		20	45	80	mV
Reset Pulse Delay	t _{RD}	C _{CT} = 100nF, t _R ≥ 100μs	55	105	180	ms
RES Output-Low Voltage	V_{RL}	$V_S \ge 1.5V$, $R_{RES} = 4k\Omega$ to V_{OUT}			0.4	V
RES Output-High Leakage Current	I _{RH}	V _{RES} = 3.3V			1.0	μΑ
Delay Comparator Threshold	VCTTH	V _{CT} rising	1.9	2.1	2.4	V
Delay Comparator Threshold Hysteresis				100		mV

MIXIM

ELECTRICAL CHARACTERISTICS (MAX5091B) (continued)

 $(V_S = +14V, V_{OUT} = 3.3V, EN$ unconnected, $T_A = T_J = -40^{\circ}C$ to $+125^{\circ}C, C_{IN} = 10\mu F, C_{OUT} = 10\mu F$, unless otherwise noted. Typical specifications are at $T_A = +25^{\circ}C$.) (Note 1)

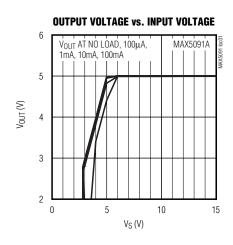
PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
SENSE						
Sense Threshold	V _{ST}	V _{SI} falling	1.09	1.15	1.23	V
Sense Threshold Hysteresis			50	100	150	mV
Sense Output-Low Voltage	V _{SL}	$V_{SI} \le 1.09V$, $V_S \ge 4V$, $R_{SO} = 10k\Omega$ to V_{OUT}			0.4	V
Sense Output Leakage Current	Ish	V _{SO} = 3.3V, V _{SI} ≥ 1.5V			1	μΑ
Sense Input Current	I _{SI}	V _{SI} = 3.3V	3.3V -1 +1		+1	μΑ
ENABLE						
Enable Valtage	\/=	EN = high, regulator on	2.4			V
Enable Voltage	V _{EN}	EN = low, regulator off			0.4	V
Enable Internal Pullup Current	IEN	EN is internally pulled up to 3.6V (max)	3		μΑ	

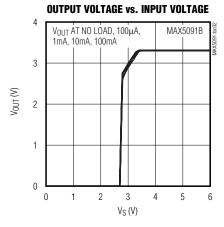
Note 1: Limits at $T_A = -40$ °C are guaranteed by design and not production tested.

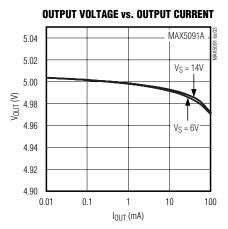
Note 2: Maximum output current is limited by the power dissipation capability of the package.

Typical Operating Characteristics

(Typical Application Circuit, $V_S = +14V$, $C_{IN} = 10\mu F$, $C_{OUT} = 10\mu F$, $V_{SI} = 0V$, $V_{EN} = +2.4V$, $V_{OUT} = +5V$, $T_A = +25^{\circ}C$, unless otherwise noted.)

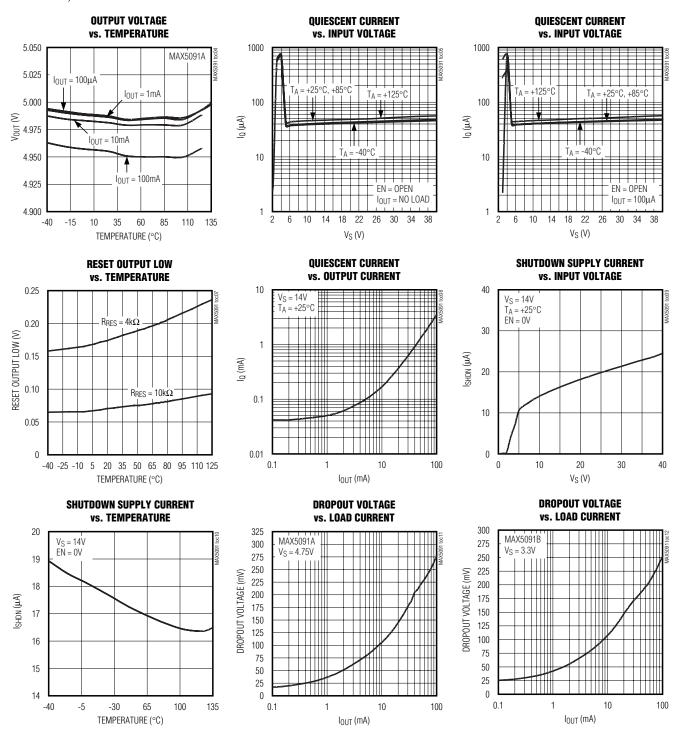






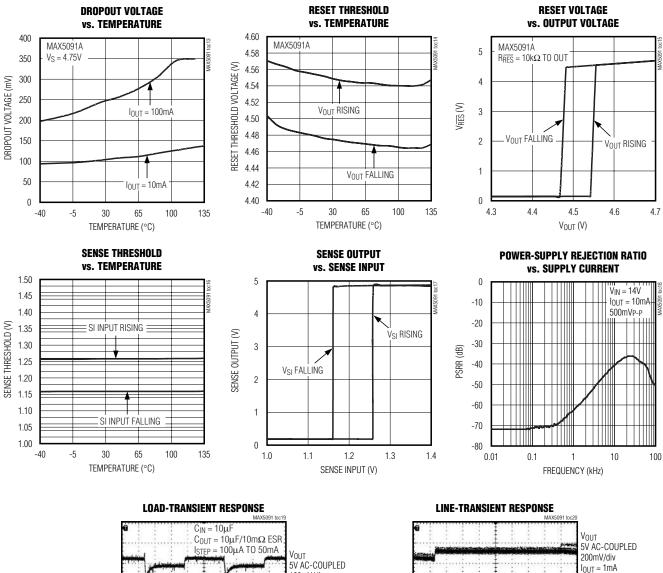
Typical Operating Characteristics (continued)

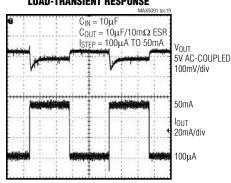
(Typical Application Circuit, $V_S = +14V$, $C_{IN} = 10\mu F$, $C_{OUT} = 10\mu F$, $V_{SI} = 0V$, $V_{EN} = +2.4V$, $V_{OUT} = +5V$, $T_A = +25^{\circ}C$, unless otherwise noted.)



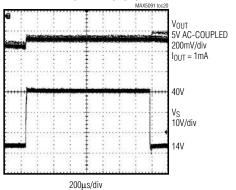
Typical Operating Characteristics (continued)

(Typical Application Circuit, $V_S = +14V$, $C_{IN} = 10\mu F$, $C_{OUT} = 10\mu F$, $V_{SI} = 0V$, $V_{EN} = +2.4V$, $V_{OUT} = +5V$, $T_A = +25^{\circ}C$, unless otherwise noted.)



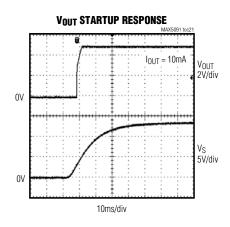


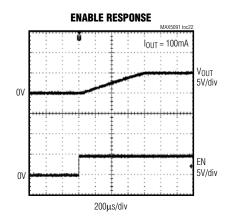
200µs/div

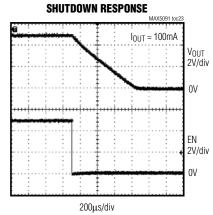


Typical Operating Characteristics (continued)

(Typical Application Circuit, $V_S = +14V$, $C_{IN} = 10\mu F$, $C_{OUT} = 10\mu F$, $V_{SI} = 0V$, $V_{EN} = +2.4V$, $V_{OUT} = +5V$, $T_A = +25^{\circ}C$, unless otherwise noted.)







Pin Description

PIN	NAME	FUNCTION
1	Vs	Regulator Input. Operating supply range is from +5V to +28V and withstands 40V transients. Bypass Vs to GND with a 10µF capacitor.
2	SI	Voltage Sense/Power-Fail Comparator Input. SI is the noninverting input of an uncommitted comparator. SO asserts low if V _{SI} drops below the reference level, V _{ST} .
3	EN	Enable Input. Leave unconnected (or pull EN high) to turn on the regulator. Pull EN low to place the device in shutdown mode. EN is internally pulled up to 3.6V.
4	СТ	Reset Timeout Delay Capacitor Connection. Connect a capacitor from CT to GND to program the reset timeout period/reset pulse delay. During regulation, CT is pulled up to V _{OUT} . CT is pulled low during reset, when EN is low, or when in thermal shutdown.
5	GND	Ground. Bypass the input and output capacitors to the GND plane. Solder to large pads or the circuit-board ground plane to maximize thermal dissipation.
6	RES	Active-Low Reset Output. Pull up externally to V _{OUT} . Open-drain RES goes low when V _{OUT} is below the reset threshold. Once output voltage is in regulation, RES goes high after the programmed reset timeout period is over. RES is low when EN is low or in thermal shutdown.
7	SO	Voltage Sense/Power-Fail Comparator Output. Pull up externally to V _{OUT} . Open-drain SO asserts low when V _{SI} drops below the reference level, V _{ST} . SO also asserts low when EN is low or in thermal shutdown.
8	Vout	Regulator Output. Fixed at +5V (MAX5091A) or +3.3V (MAX5091B). Bypass with a 10µF ceramic capacitor to GND.
EP	EP	Exposed Paddle. EP is internally connected to GND. Connect EP to GND to provide a low thermal-resistance path from the IC junction to the PC board. Do not use as the only electrical connection to GND.

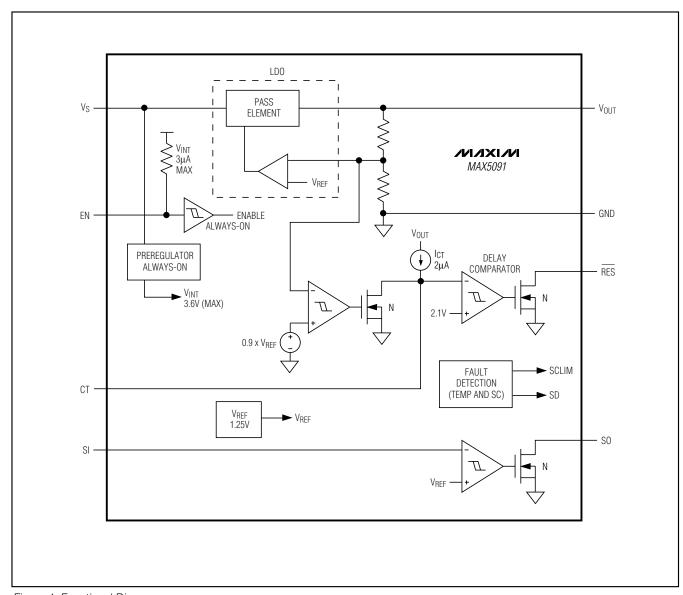


Figure 1. Functional Diagram

Detailed Description

Regulator

The MAX5091 high-voltage, LDO regulator operates from +5V to +28V input voltage. The device withstands up to 40V transients, providing protection against temporary overvoltage conditions like load dump. The MAX5091 incorporates internal feedback resistors for factory-preset voltages of either +5V (MAX5091A) or +3.3V (MAX5091B). The regulator is capable of driving up to 100mA of load current and features a typical current limit of 260mA. The regulator uses a pnp pass element and provides low 0.5V dropout while delivering 100mA load current. The output of the regulator follows closely to the input during turn-on. See the Output Voltage vs. Input Voltage graph in the Typical Operating Characteristics. This makes the usable input voltage range for 3.3V and 5V output down to 3.7V and 5.5V, respectively. The MAX5091 is designed to operate with very low quiescent current during always-on operation when not in dropout. The regulator is stable with a wide variety of capacitors including low-ESR ceramic 10µF (0603 case size). The load-transient response curves depict the stability of the LDO when using different capacitance and ESR ranges. See the Capacitor Selection and Regulator Stability section in the Applications Information.

Reset Output (RES)

The MAX5091 integrates a power-on-reset circuit. \overline{RES} is an open-drain output that requires a pullup resistor to VOUT. The open-drain MOSFET can sink up to 825 μ A current while keeping the \overline{RES} voltage below 0.4V. The internal reset circuit monitors the regulator output voltage and \overline{RES} asserts an active-low output when the regulator output falls below a reset threshold of typically 0.9 x VOUT. The \overline{RES} output remains low when VOUT is below the reset threshold, and remains low for the duration of the reset timeout period (tRD). The reset timeout period is programmable and can be set with an external capacitor connected from CT to ground. The duration of the delay as a function of CT is:

$$t_{RD} = \frac{C_{CT} \times V_{CCTH}}{I_{CT}} + (35 \times 10^{-6})$$

where V_{CCTH} = 2.1V and I_{CT} = 2 \times $10^{-6}\,A.$

The default reset timeout period is 35µs when no capacitor is connected from CT to ground.

SI/SO Comparator

The MAX5091 includes an uncommitted comparator for monitoring the input voltage or for detecting power-fail conditions. The input SI is the noninverting input of the comparator. The open-drain output SO asserts low when voltage at the input SI drops below the threshold voltage, VST (see Figure 1). The sense comparator typically has a hysteresis of 100mV. Use the following equation to calculate the resistor-divider for programming the trip voltage (VTRIP) during power-fail. See the *Typical Application Circuit*.

$$V_{TRIP} = \frac{(V_{ST} \times R_H)}{R_L} + V_{ST}$$

where V_{ST} = 1.16V (typ). Choose RL between 100k Ω to 300k $\Omega.$

Enable Input

The enable (EN) is a TTL-compatible logic input. Logic low at EN turns off the regulator and reduces the current consumption to $17\mu\text{A}$ (typ). It is internally pulled up to a logic-high voltage (3.6V max) by an internal resistor. Thus, the MAX5091 is enabled by default when Vs is applied and EN is left unconnected. The regulator, reset supervisor circuit, and the sense comparator can be manually shut down by pulling EN low. For shutdown operation, the pulldown network must be capable of sinking $3\mu\text{A}$ max, since the internal pullup resistor sets the maximum pullup current at $3\mu\text{A}$. The external pulldown device should not leak more than $1\mu\text{A}$ current when it is in the off-state.

Current Limit

The MAX5091 features a current limiter that monitors the output current and controls the pass transistor's gate voltage, limiting the output current to typically 260mA. The output can be continuously shorted to ground without damaging the device at $V_S \le 16V$. Note that the output short-circuit current may increase the power dissipation significantly and raise the junction temperature to its thermal-shutdown threshold. In such a case, the MAX5091 is temporarily turned off.

Thermal Shutdown

When the junction temperature exceeds $T_J = +165^{\circ}C$ (typ), an internal thermal sensor signals the shutdown logic to turn off the pass transistor and allow the IC to cool. The thermal sensor turns the pass transistor on again after the IC's junction temperature cools by $+20^{\circ}C$ (typ), resulting in a cycled output during continuous thermal-overload conditions. Thermal shutdown protects the MAX5091 in the event of fault conditions. For continuous operation, do not exceed the absolute maximum junction temperature of $T_{JJ} = +150^{\circ}C$.

Applications Information

Available Output Current Calculation

The MAX5091 high-voltage regulator provides up to 100mA of output current. The input voltage extends to +28V. Package power dissipation limits the amount of output current available for a given input/output voltage and ambient temperature. Figure 2 depicts the maximum power dissipation curve for the 8-pin SO-EP package. The graph assumes that the exposed metal back of the MAX5091 package is soldered to copper on a single layer PCB according to the JEDEC51 standard.

Use Figure 2 to determine the allowable package dissipation for a given ambient temperature. Alternately, use the following formula to calculate the allowable package dissipation:

$$P_D \ = \begin{cases} 1.538W \ \text{For} \ T_A \ \le +70^{\circ}\text{C} \\ 1.538 - 0.01923 \ (T_A - 70^{\circ}\text{C}) \ \text{For} \ +70^{\circ}\text{C} < \ T_A \ \le +125^{\circ}\text{C} \end{cases}$$

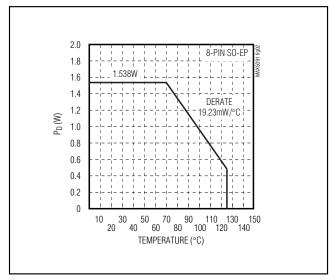


Figure 2. 8-Pin SO-EP Maximum Power Dissipation vs. Temperature

After determining the allowable package dissipation, calculate the maximum output current using the following formula:

$$I_{OUT(MAX)} \cong \frac{P_D}{V_S - V_{OUT}}$$

The above equations do not include the power dissipation from self-heating due to the IC ground current.

The junction-to-ambient thermal impedance depends on the area of the copper plane, its thickness, and the number of copper layers on PCB. For the higher power dissipation requirement, use multiple-layered PCBs with 2oz copper and a large copper area.

Capacitor Selection and Regulator Stability

For stable operation over the full temperature range and with load currents up to 100mA, use a 10µF output capacitor with a low ESR. Table 1 shows a list of recommended output capacitor ESR for various load conditions.

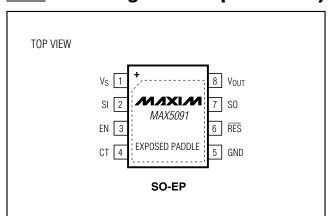
Table 1. Recommended Output Capacitor ESR

RECOMMENDED COUT ESR							
I _{OUT} V _{OUT} = 3.3V V _{OUT} = 5.0V							
I _{OUT} ≤ 10mA	$C_{\rm ESR} < 0.66\Omega$	$C_{\text{ESR}} < 1\Omega$					
I _{OUT} ≤ 50mA	$C_{\text{ESR}} < 0.132\Omega$	$C_{\text{ESR}} < 0.2\Omega$					
I _{OUT} ≤ 100mA	$C_{ESR} < 66 m\Omega$	$C_{ESR} < 0.1\Omega$					

PROCESS: BiCMOS

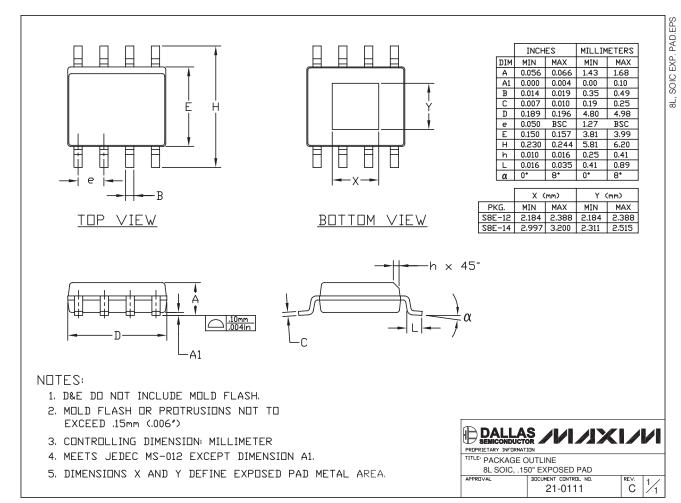
Pin Configurations (continued)

__Chip Information



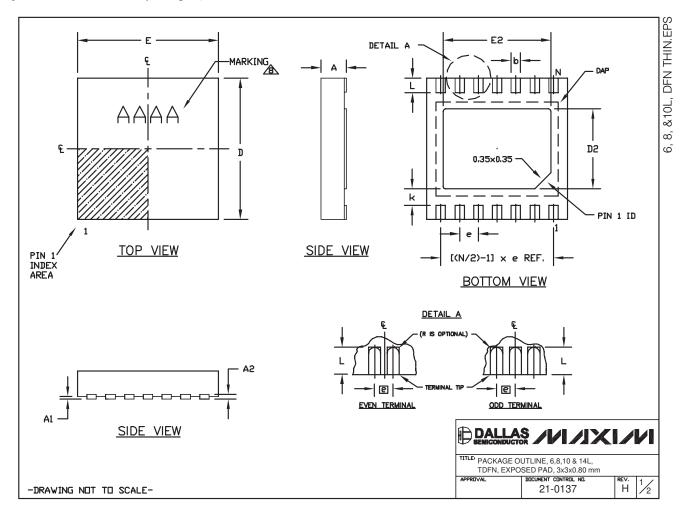
Package Information

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to www.maxim-ic.com/packages.)



Package Information (continued)

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to www.maxim-ic.com/packages.)



Package Information (continued)

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to www.maxim-ic.com/packages.)

COMMON DIMENSIONS							
SYMBOL	MIN.	MAX.					
Α	0.70	0.80					
D	2.90	3.10					
Е	2.90	3.10					
A1	0.00	0.05					
L	0.20	0.40					
k	0.25 MIN.						
A2	0.20 REF.						

PACKAGE VARIATIONS									
PKG. CODE	N	D2	E2	е	JEDEC SPEC	b	[(N/2)-1] x e		
T633-1	6	1.50±0.10	2.30±0.10	0.95 BSC	MO229 / WEEA	0.40±0.05	1.90 REF		
T633-2	6	1.50±0.10	2.30±0.10	0.95 BSC	MO229 / WEEA	0.40±0.05	1.90 REF		
T833-1	8	1.50±0.10	2.30±0.10	0.65 BSC	MO229 / WEEC	0.30±0.05	1.95 REF		
T833-2	8	1.50±0.10	2.30±0.10	0.65 BSC	MO229 / WEEC	0.30±0.05	1.95 REF		
T833-3	8	1.50±0.10	2.30±0.10	0.65 BSC	MO229 / WEEC	0.30±0.05	1.95 REF		
T1033-1	10	1.50±0.10	2.30±0.10	0.50 BSC	MO229 / WEED-3	0.25±0.05	2.00 REF		
T1033-2	10	1.50±0.10	2.30±0.10	0.50 BSC	MO229 / WEED-3	0.25±0.05	2.00 REF		
T1433-1	14	1.70±0.10	2.30±0.10	0.40 BSC		0.20±0.05	2.40 REF		
T1433-2	14	1.70±0.10	2.30±0.10	0.40 BSC		0.20±0.05	2.40 REF		

- 1. ALL DIMENSIONS ARE IN mm. ANGLES IN DEGREES.
 2. COPLANARITY SHALL NOT EXCEED 0.08 mm.
 3. WARPAGE SHALL NOT EXCEED 0.10 mm.

- 4. PACKAGE LENGTH/PACKAGE WIDTH ARE CONSIDERED AS SPECIAL CHARACTERISTIC(S).
- 4. PACKAGE LENGTH/PACKAGE WIDTH ARE CONSIDERED AS SPECIAL CHARACTERISTIC(S).
 5. DRAWING CONFORMS TO JEDEC MO229, EXCEPT DIMENSIONS "D2" AND "E2", AND T1433—1 & T1433—2.
 6. "N" IS THE TOTAL NUMBER OF LEADS.
 7. NUMBER OF LEADS SHOWN ARE FOR REFERENCE ONLY.
 8. MARKING IS FOR PACKAGE ORIENTATION REFERENCE ONLY.

DALLAS / VI/JXI/VI PACKAGE OUTLINE, 6,8,10 & 14L, TDFN, EXPOSED PAD, 3x3x0.80 mm

21-0137

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-DRAWING NOT TO SCALE-

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